

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-40	V
Collector-Emitter Voltage	V _{CEO}	-32	V
Emitter-Base Voltage	V _{EBO}	-5	V
Continuous Collector Current	I _C	-2	A
Peak Pulse Collector Current	I _{CM}	-3	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	1.2	W
Power Dissipation @T _L = +25°C (Note 6)	P _D	15	W
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	104	°C/W
Thermal Resistance, Junction to Lead (Note 6)	R _{θJL}	8.3	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

ESD Ratings (Note 7)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Note:
- For a device mounted with the exposed collector pad on minimum recommended pad (MRP) layout 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
 - Thermal resistance from junction to solder-point (on the exposed collector pad).
 - Refer to JEDEC specification JESD22-A114 and JESD22-A115.

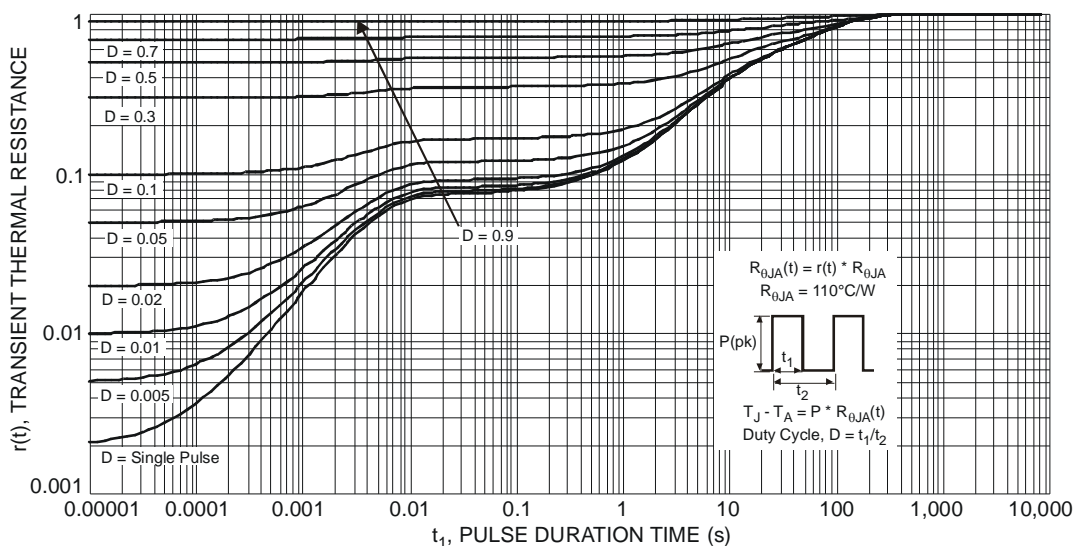
Thermal Characteristics


Figure 1 Transient Thermal Response

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Collector-Base Breakdown Voltage	BV _{CBO}	-40	—	—	V	I _C = -50μA, I _E = 0
Collector-Emitter Breakdown Voltage	BV _{CEO}	-32	—	—	V	I _C = -1mA, I _B = 0
Emitter-Base Breakdown Voltage	BV _{EBO}	-5	—	—	V	I _E = -50μA, I _C = 0
Collector Cutoff Current	I _{CBO}	—	—	-1	μA	V _{CB} = -20V, I _E = 0
Emitter Cutoff Current	I _{EBO}	—	—	-1	μA	V _{EB} = -4V, I _C = 0
ON CHARACTERISTICS (Note 8)						
Collector-Emitter Saturation Voltage	V _{CE(sat)}	—	—	-0.8	V	I _C = -2A, I _B = -0.2A
DC Current Gain	h _{FE}	120	—	270	—	V _{CE} = -3V, I _C = -0.5A
SMALL SIGNAL CHARACTERISTICS						
Current Gain-Bandwidth Product	f _T	—	110	—	MHz	V _{CE} = -5V, I _C = -0.1A, f = 30MHz
Output Capacitance	C _{obo}	—	26	—	pF	V _{CB} = -10V, f = 1MHz
Turn-On Time	t _{on}	—	109	—	ns	V _{CC} = 30V I _{CC} = 150mA I _{B1} = -I _{B2} = 15mA
Delay Time	t _d	—	60	—	ns	
Rise Time	t _r	—	49	—	ns	
Turn-Off Time	t _{off}	—	280	—	ns	
Storage Time	t _s	—	246	—	ns	
Fall Time	t _f	—	34	—	ns	

Note: 8. Measured under pulsed conditions. Pulse width = 300μs. Duty cycle ≤ 2%.

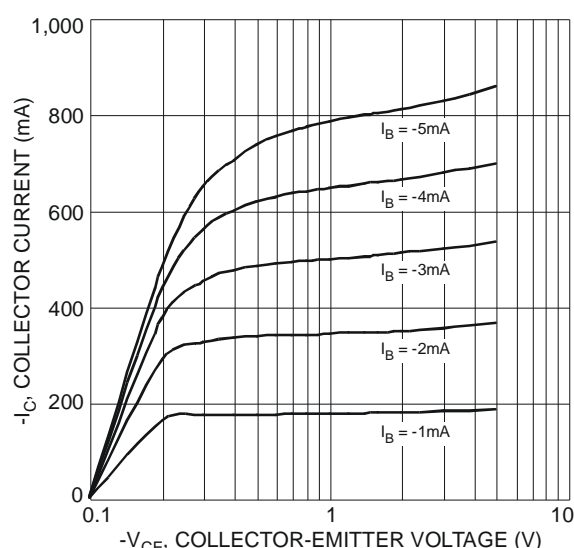
Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)


Figure 2 Typical Collector Current vs. Collector-Emitter Voltage

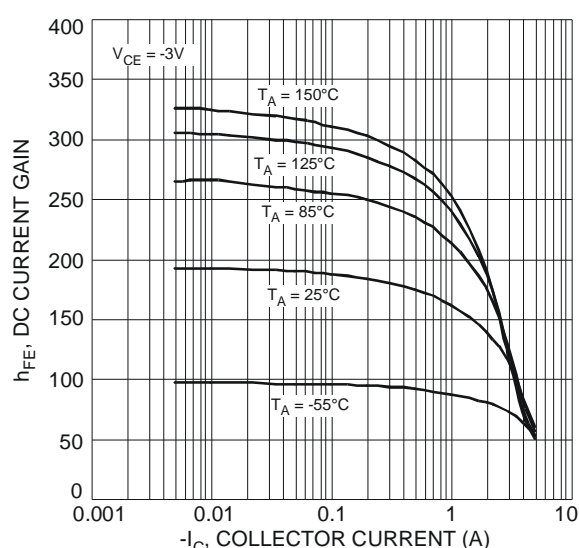


Figure 3 Typical DC Current Gain vs. Collector Current

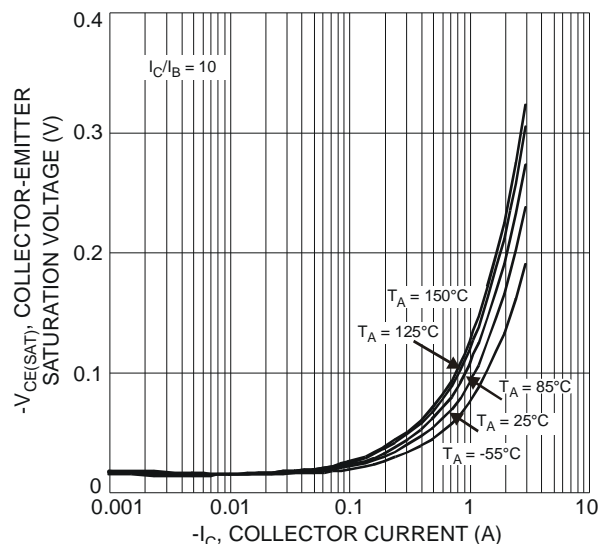


Figure 4 Typical Collector-Emitter Saturation Voltage vs. Collector Current

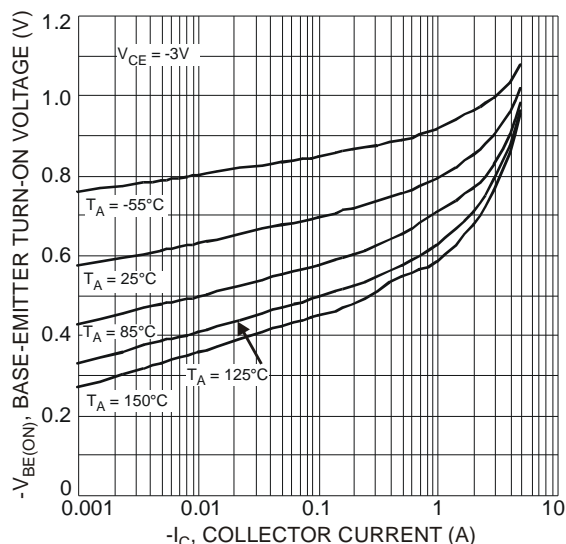


Figure 5 Typical Base-Emitter Turn-On Voltage vs. Collector Current

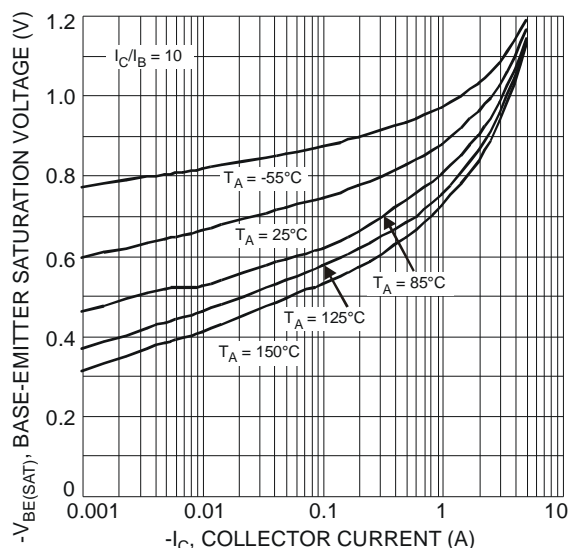


Figure 6 Typical Base-Emitter Saturation Voltage vs. Collector Current

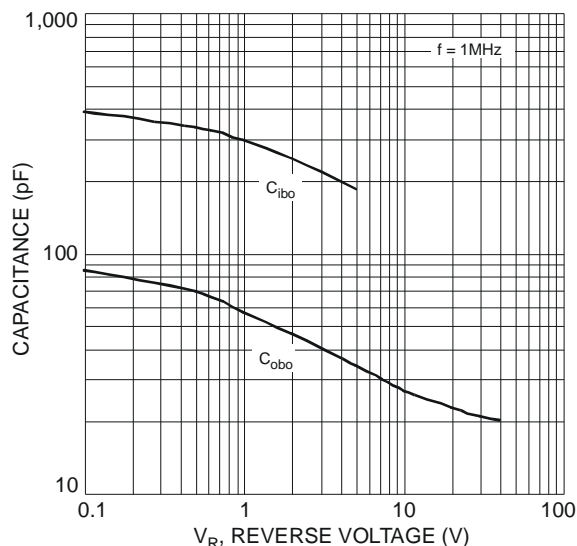


Figure 7 Typical Capacitance Characteristics

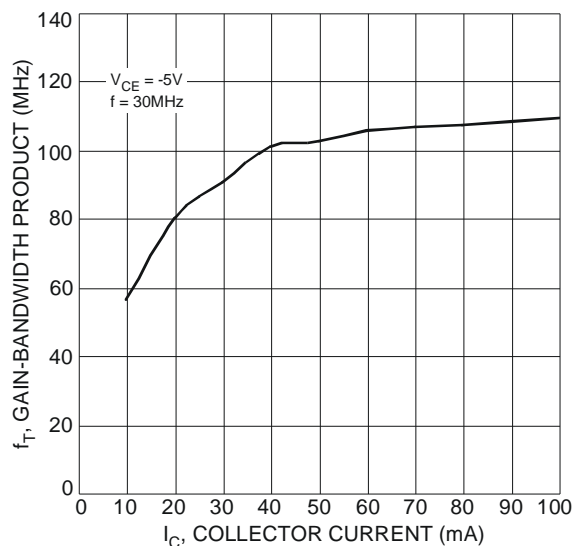
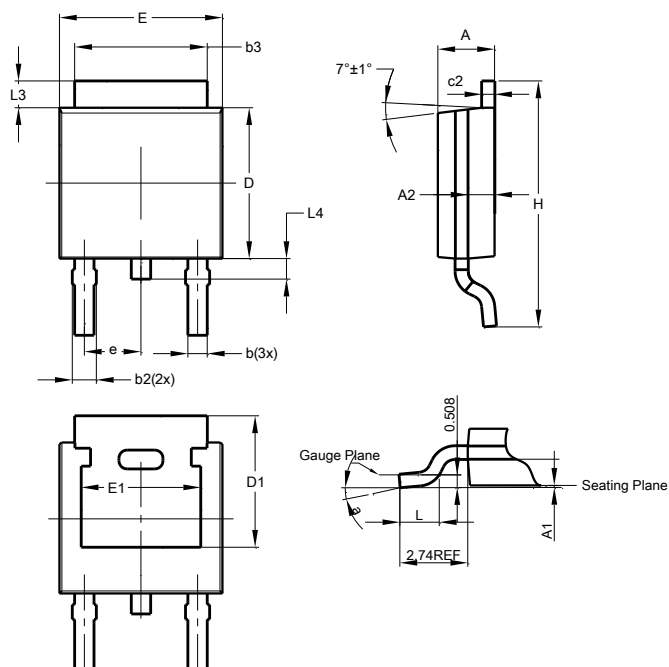


Figure 8 Typical Gain-Bandwidth Product vs. Collector Current

Package Outline Dimensions

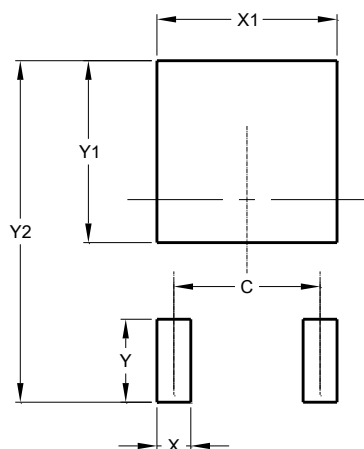
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



TO252 (DPAK)			
Dim	Min	Max	Typ
A	2.19	2.39	2.29
A1	0.00	0.13	0.08
A2	0.97	1.17	1.07
b	0.64	0.88	0.783
b2	0.76	1.14	0.95
b3	5.21	5.46	5.33
c2	0.45	0.58	0.531
D	6.00	6.20	6.10
D1	5.21	-	-
e	-	-	2.286
E	6.45	6.70	6.58
E1	4.32	-	-
H	9.40	10.41	9.91
L	1.40	1.78	1.59
L3	0.88	1.27	1.08
L4	0.64	1.02	0.83
a	0°	10°	-
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	4.572
X	1.060
X1	5.632
Y	2.600
Y1	5.700
Y2	10.700

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